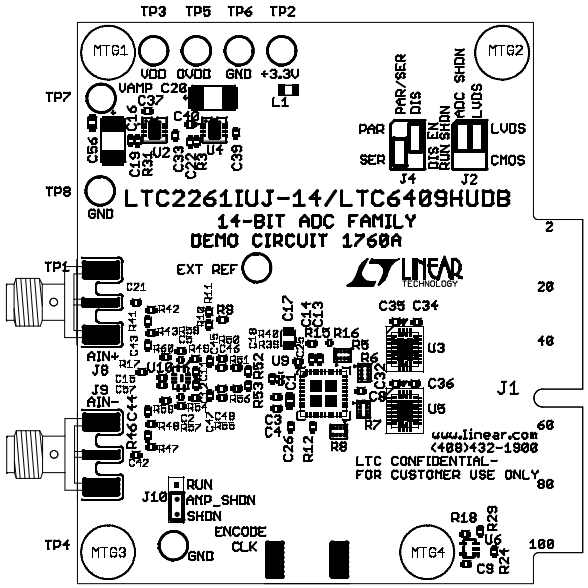
REVISION HISTORY				
ECO	REV	DESCRIPTION	APPROVED	DATE
	2	PRODUCTION	CLARENCE M.	01-24-11



TOP SILKSCREEN

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELCIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS ON MTG1-MTG4 AND FROM THE BOTTOM SIDE.

APPROVALS	
PCB DES.	KT
APP ENG.	CLARENCE M.
1/24/2011 02:17:34p	

LINEAR TECHNOLOGY
1630 McCARTHY BLVD
MILPITAS, CA 95035
TEL: (408)432-1900 www.linear.com
FAX: (408)434-0507
LTC CONFIDENTIAL-FOR CUSTOMER USE ONLY

TITLE: TOP ASSEMBLY DRAWING

14-BIT ADC FAMILY

SIZE	IC NO.	REV.
N/A	LTC2261IUJ-14/LTC6409HUDB DEMO CIRCUIT 1760A	2

SCALE: NONE	FILENAME: DC1760A-2	SHEET 1 OF 2